

# SN54ALS165, SN74ALS165 PARALLEL-LOAD 8-BIT REGISTERS

SDAS157B – JUNE 1982 – REVISED DECEMBER 1994

- Complementary Outputs
- Direct Overriding Load (Data) Inputs
- Gated Clock Inputs
- Parallel-to-Serial Data Conversion
- Package Options Include Plastic Small-Outline (D) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

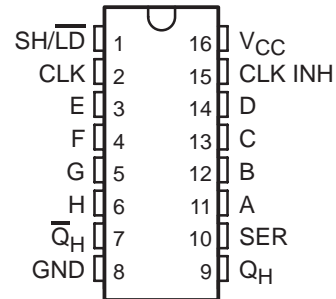
## description

The 'ALS165 are parallel-load 8-bit serial shift registers that, when clocked, shift the data toward serial ( $Q_H$  and  $\bar{Q}_H$ ) outputs. Parallel-in access to each stage is provided by eight individual direct data (A–H) inputs that are enabled by a low level at the shift/load ( $SH/\bar{LD}$ ) input. The 'ALS165 have a clock-inhibit function and complemented serial outputs.

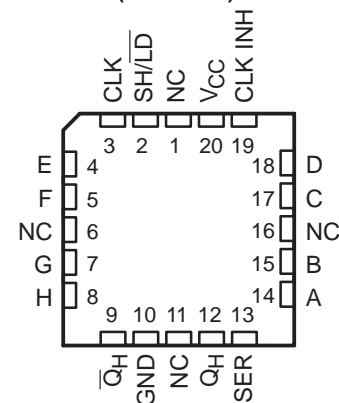
Clocking is accomplished by a low-to-high transition of the clock (CLK) input while  $SH/\bar{LD}$  is held high and the clock inhibit (CLK INH) input is held low. The functions of CLK and CLK INH are interchangeable. Since a low CLK and a low-to-high transition of CLK INH also accomplishes clocking, CLK INH should be changed to the high level only while CLK is high. Parallel loading is inhibited when  $SH/\bar{LD}$  is held high. The parallel inputs to the register are enabled while  $SH/\bar{LD}$  is low independently of the levels of the CLK, CLK INH, or serial (SER) inputs.

The SN54ALS165 is characterized for operation over the full military temperature range of  $-55^{\circ}\text{C}$  to  $125^{\circ}\text{C}$ . The SN74ALS165 is characterized for operation from  $0^{\circ}\text{C}$  to  $70^{\circ}\text{C}$ .

SN54ALS165 . . . J PACKAGE  
SN74ALS165 . . . D OR N PACKAGE  
(TOP VIEW)



SN54ALS165 . . . FK PACKAGE  
(TOP VIEW)



NC – No internal connection

FUNCTION TABLE

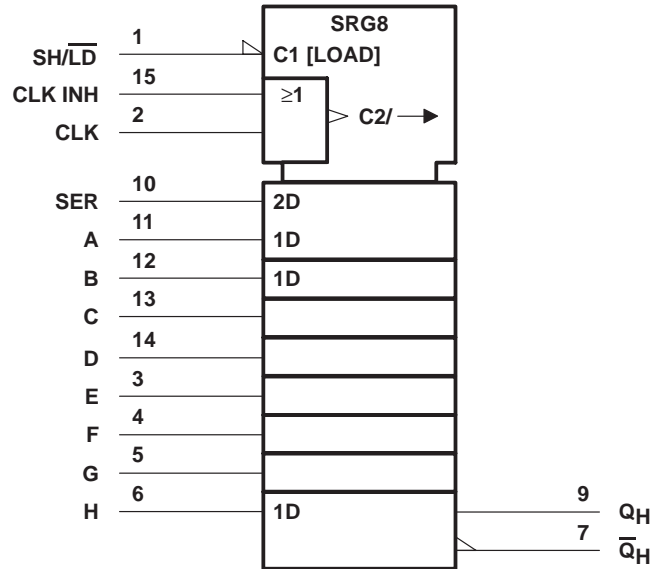
INPUTS			FUNCTION
$SH/\bar{LD}$	CLK	CLK INH	
L	X	X	Parallel load
H	H	X	No change
H	X	H	No change
H	L	↑	Shift†
H	↑	L	Shift†

† Shift = content of each internal register shifts toward serial outputs. Data at SER is shifted into first register.

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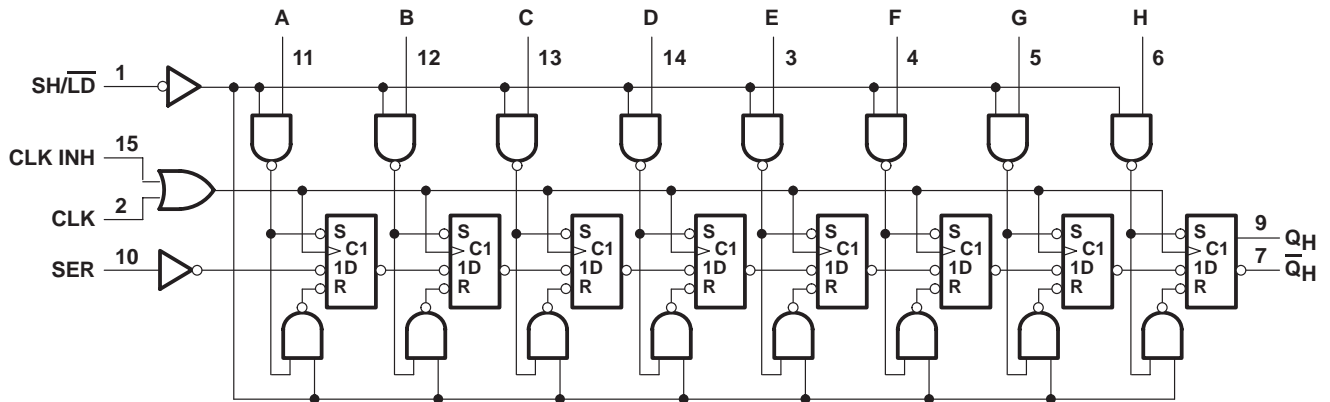
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## logic symbol†



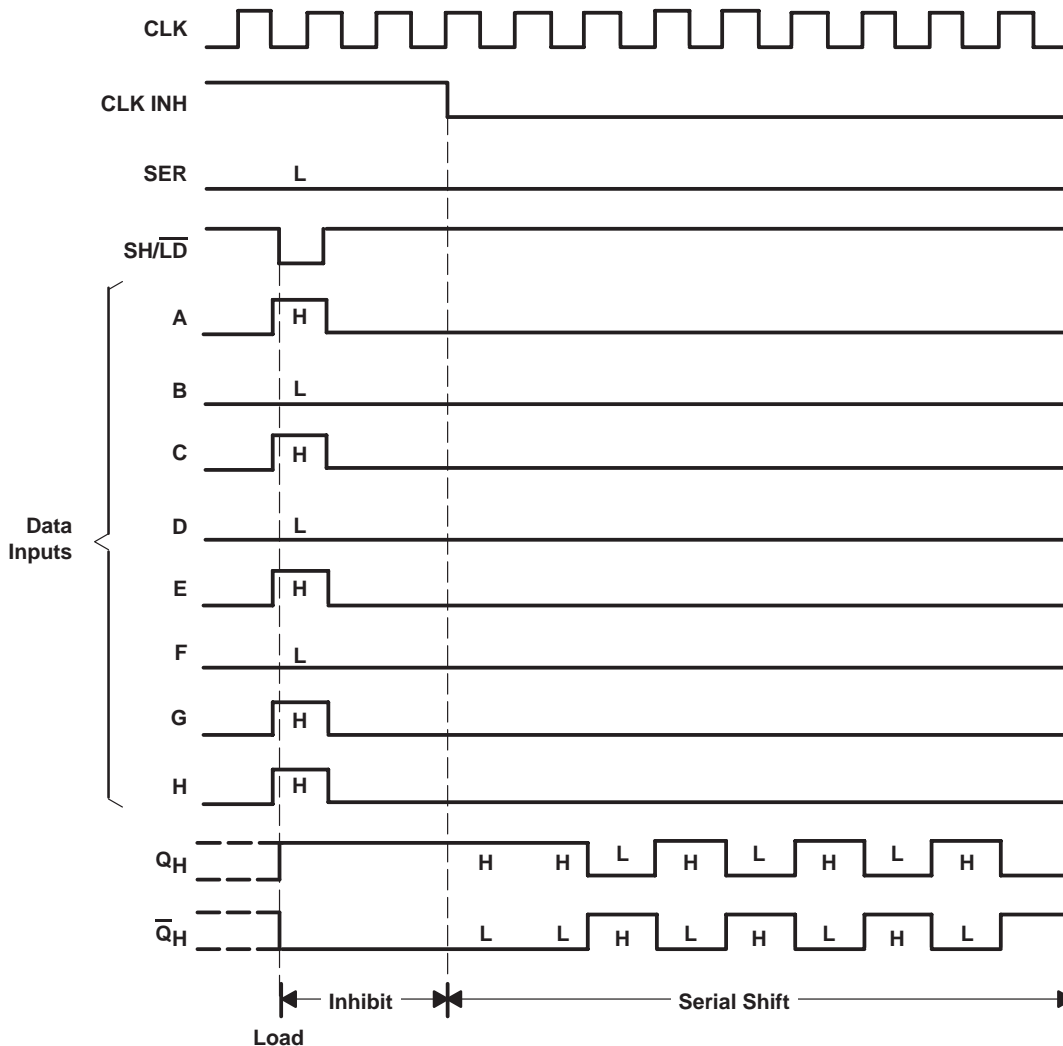
† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.  
Pin numbers shown are for the D, J, and N packages.

## logic diagram (positive logic)



Pin numbers shown are for the D, J, and N packages.

typical shift, load, and inhibit sequences



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, $V_{CC}$ .....	7 V
Input voltage, $V_I$ .....	7 V
Operating free-air temperature range, $T_A$ : SN54ALS165 .....	-55°C to 125°C
SN74ALS165 .....	0°C to 70°C
Storage temperature range .....	-65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

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## recommended operating conditions

		SN54ALS165			SN74ALS165			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
$V_{CC}$	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
$V_{IH}$	High-level input voltage	2			2			V
$V_{IL}$	Low-level input voltage			0.7			0.8	V
$I_{OH}$	High-level output current			-0.4			-0.4	mA
$I_{OL}$	Low-level output current			4			8	mA
$f_{clock}$	Clock frequency	0		35	0		45	MHz
$t_w(\text{CLK})$	Pulse duration, CLK (see Figure 1)	CLK high		14		11		ns
		CLK low		14		11		
$t_w(\text{load})$	Pulse duration, SH/LD low			15		12		ns
$t_{su1}$	Setup time, clock enable (see Figure 1)			15		11		ns
$t_{su2}$	Setup time, parallel input (see Figure 1)			11		10		ns
$t_{su3}$	Setup time, serial input (see Figure 2)			11		10		ns
$t_{su4}$	Setup time, shift (see Figure 2)			15		10		ns
$t_h$	Hold time at any input			4		4		ns
$T_A$	Operating free-air temperature	-55		125	0		70	°C

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	SN54ALS165			SN74ALS165			UNIT
		MIN	TYP†	MAX	MIN	TYP†	MAX	
$V_{IK}$	$V_{CC} = 4.5\text{ V}$ , $I_I = -18\text{ mA}$			-1.5			-1.5	V
$V_{OH}$	$V_{CC} = 4.5\text{ V to } 5.5\text{ V}$ , $I_{OH} = -0.4\text{ mA}$	$V_{CC} - 2$			$V_{CC} - 2$			V
$V_{OL}$	$V_{CC} = 4.5\text{ V}$	$I_{OL} = 4\text{ mA}$	0.25	0.4	0.25	0.4	V	
		$I_{OL} = 8\text{ mA}$			0.35	0.5		
$I_I$	$V_{CC} = 5.5\text{ V}$ , $V_I = 7\text{ V}$			0.1		0.1	mA	
$I_{IH}$	$V_{CC} = 5.5\text{ V}$ , $V_I = 2.7\text{ V}$			20		20	μA	
$I_{IL}$	$V_{CC} = 5.5\text{ V}$ , $V_I = 0.4\text{ V}$			-0.1		-0.1	mA	
$I_{O\ddagger}$	$V_{CC} = 5.5\text{ V}$ , $V_O = 2.25\text{ V}$	-20		-112	-30		-112	mA
$I_{CC}$	$V_{CC} = 5.5\text{ V}$ , See Note 1		12	24		12	24	mA

† All typical values are at  $V_{CC} = 5\text{ V}$ ,  $T_A = 25^\circ\text{C}$ .

‡ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current,  $I_{OS}$ .

NOTE 1: With the outputs open, CLK INH and CLK at 4.5 V, and a clock pulse applied to SH/LD,  $I_{CC}$  is measured first with the parallel inputs at 4.5 V, then with the parallel inputs grounded.

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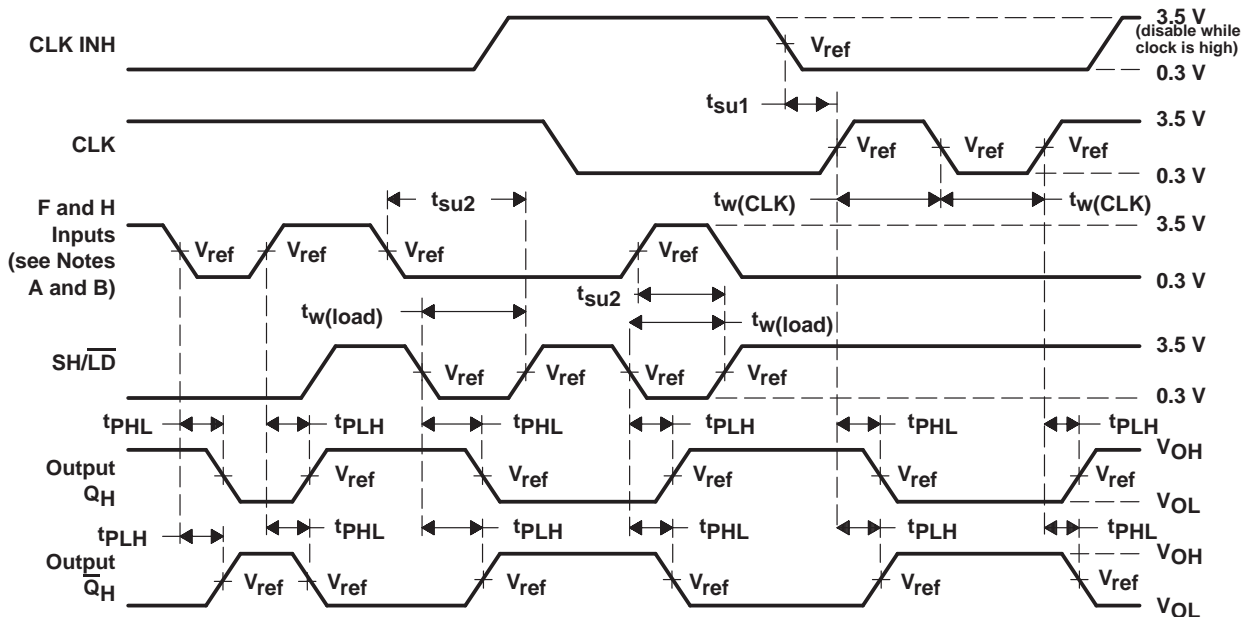
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switching characteristics (see Figures 1, 2, and 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = 4.5 V to 5.5 V, C <sub>L</sub> = 50 pF, R <sub>L</sub> = 500 Ω, T <sub>A</sub> = MIN to MAX†				UNIT
			SN54ALS165		SN74ALS165		
			MIN	MAX	MIN	MAX	
f <sub>max</sub>			35		45	MHz	
t <sub>PLH</sub>	SH/LD	Any	4	23	4	20	ns
t <sub>PHL</sub>			4	23	4	22	
t <sub>PLH</sub>	CLK	Any	3	14	3	13	ns
t <sub>PHL</sub>			3	15	3	14	
t <sub>PLH</sub>	H	Q <sub>H</sub>	3	14	3	13	ns
t <sub>PHL</sub>			3	18	3	16	
t <sub>PLH</sub>	H	Q̄ <sub>H</sub>	2	17	2	15	ns
t <sub>PHL</sub>			3	17	3	16	

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

## PARAMETER MEASUREMENT INFORMATION



- NOTES: A. The remaining six data inputs and SER are low.  
 B. Prior to test, high-level data is loaded into the H input.  
 C. The input pulse generators have the following characteristics: PRR ≤ 1 MHz, duty cycle ≤ 50%, t<sub>r</sub> = t<sub>f</sub> = 2 ns.  
 D. V<sub>ref</sub> = 1.3 V

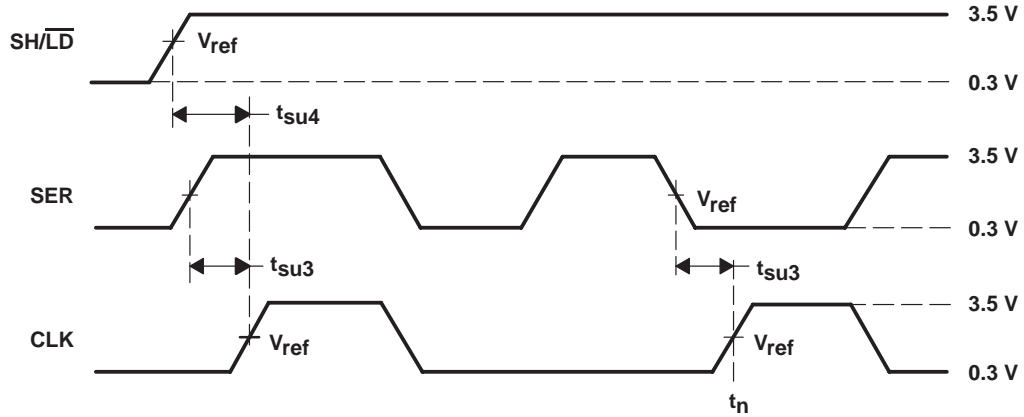
Figure 1. Voltage Waveforms



# SN54ALS165, SN74ALS165 PARALLEL-LOAD 8-BIT REGISTERS

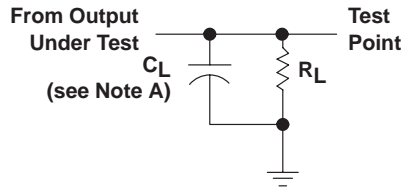
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## PARAMETER MEASUREMENT INFORMATION



- NOTES: A. The eight data inputs and CLK INH are low. Results are monitored at  $Q_H$  at  $t_n + 7$ .  
 B. The input pulse generators have the following characteristics:  $PRR \leq 1$  MHz, duty cycle = 50%,  $t_r = t_f = 2$  ns.  
 C.  $V_{ref} = 1.3$  V

Figure 2. Voltage Waveforms



NOTE A:  $C_L$  includes probe and jig capacitance.

Figure 3. Load Circuit for Switching Tests

**PACKAGING INFORMATION**

Orderable part number	Status (1)	Material type (2)	Package   Pins	Package qty   Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
<a href="#">SN74ALS165D</a>	Obsolete	Production	SOIC (D)   16	-	-	Call TI	Call TI	0 to 70	ALS165
<a href="#">SN74ALS165DR</a>	Active	Production	SOIC (D)   16	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS165
SN74ALS165DR.A	Active	Production	SOIC (D)   16	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS165
<a href="#">SN74ALS165N</a>	Active	Production	PDIP (N)   16	25   TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74ALS165N
SN74ALS165N.A	Active	Production	PDIP (N)   16	25   TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74ALS165N

(1) **Status:** For more details on status, see our [product life cycle](#).

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "-" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS165DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1



**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS165DR	SOIC	D	16	2500	353.0	353.0	32.0

**TUBE**


\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
SN74ALS165N	N	PDIP	16	25	506	13.97	11230	4.32
SN74ALS165N	N	PDIP	16	25	506	13.97	11230	4.32
SN74ALS165N.A	N	PDIP	16	25	506	13.97	11230	4.32
SN74ALS165N.A	N	PDIP	16	25	506	13.97	11230	4.32

N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN

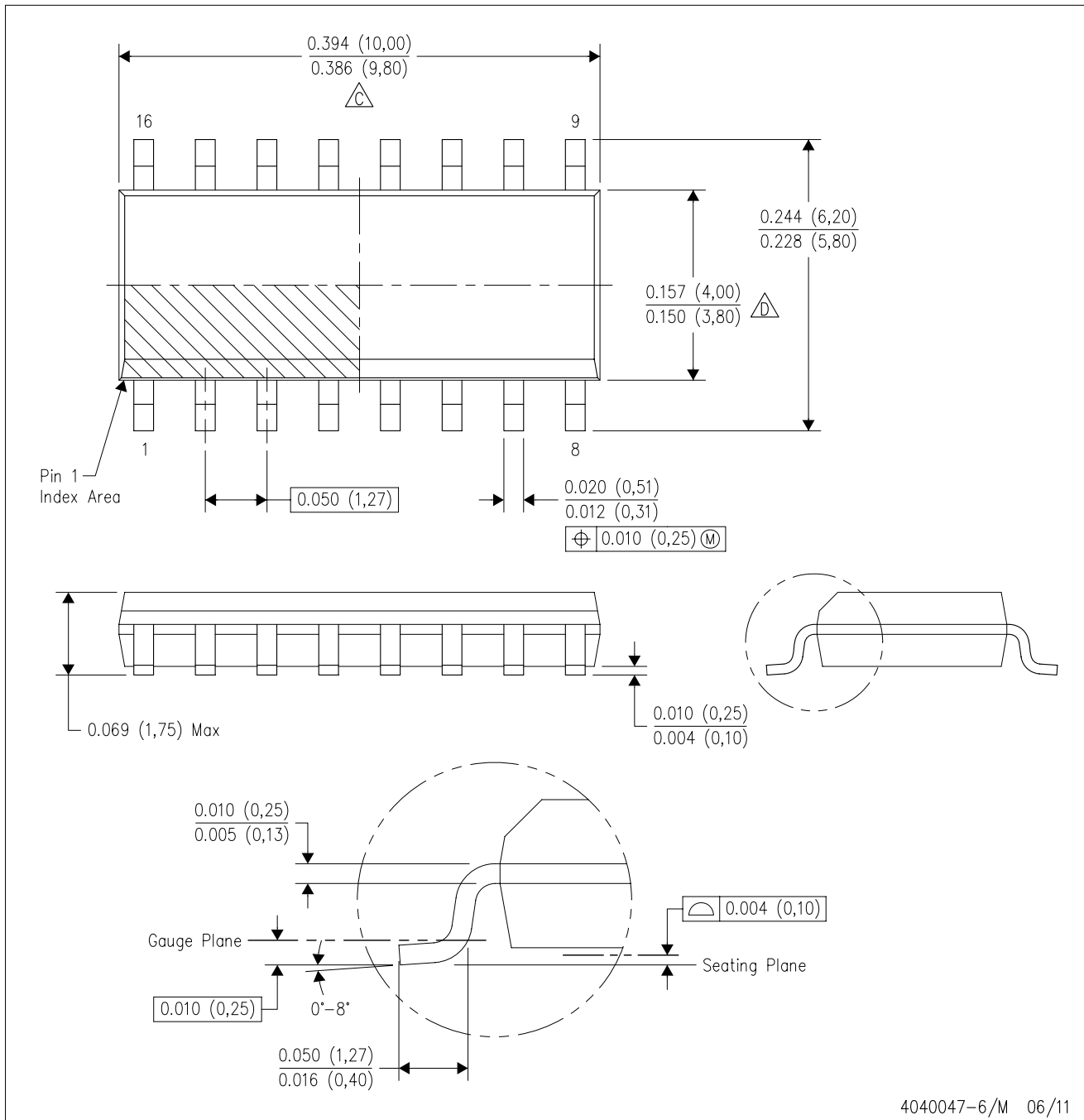


- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - D The 20 pin end lead shoulder width is a vendor option, either half or full width.

4040049/E 12/2002

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



4040047-6/M 06/11

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  -  C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
  -  D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
  - E. Reference JEDEC MS-012 variation AC.

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